



Mask Assignment and Synthesis of DSA-MP Hybrid Lithography for sub-7nm Contacts/Vias

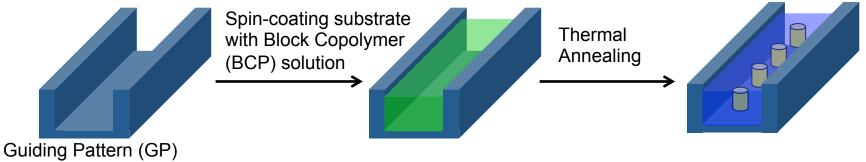
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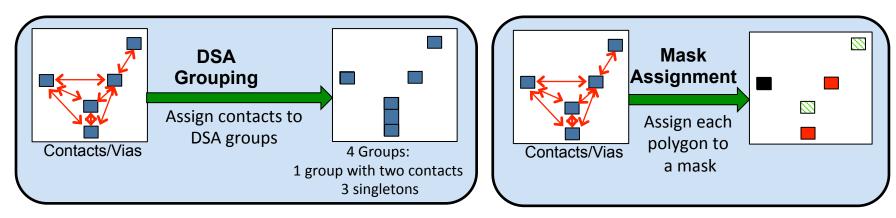
Motivation

 Directed Self Assembly (DSA) is a strong candidate for future technology nodes

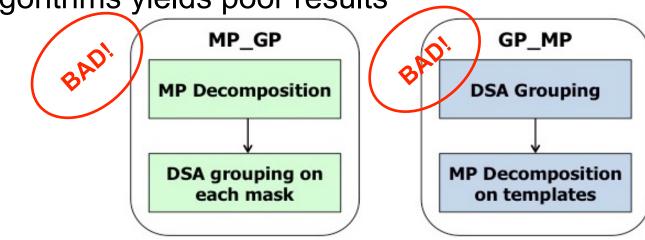


- BUT Pure DSA can not achieve 7nm node or beyond
 - Because resolution required for GP can not be delivered by 193i lithography
 - Challenges in finding BCPs which can achieve that small pitch
- Integration of DSA with Multiple Patterning (MP) is attractive for sub-7nm
 - Reduce number of masks → less costly process
 - Potentially more flexibility in polygon sizes

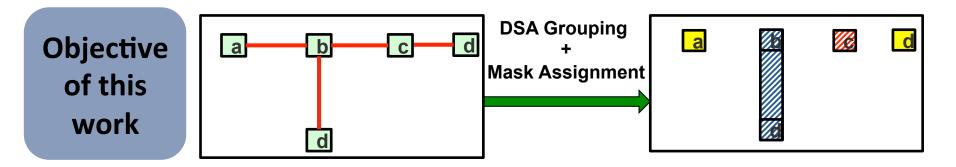
DSA Grouping and Mask Assignment

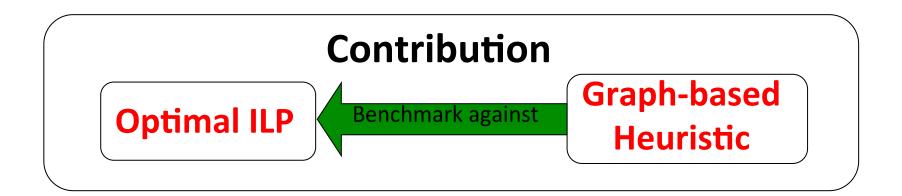


Previous work (Badr et al; SPIE'15) showed that cascading existing DSA grouping and MP decomposition algorithms yields poor results



This Work

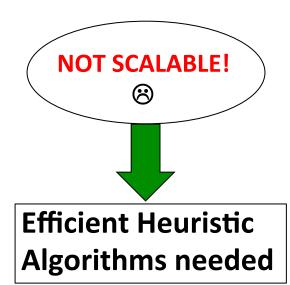




Integer Linear Programming (ILP) Formulation

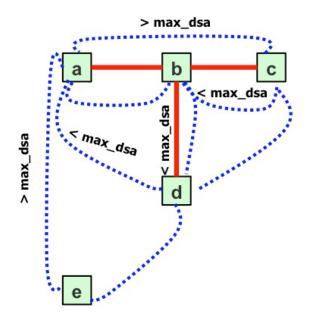
- <u>Objective</u>: minimize number of conflicts
 - A conflict is when two contacts with interdistance < litho_dist are
 - on same mask and
 - not in same DSA group
- <u>Constraints [Simplified]</u>:
 - Two "close" contacts are assigned to different masks or same DSA group if possible
 - Number of contacts in each group ≤ max_g
- ILP works for DP, TP, QP, and any number of masks that is power of two.





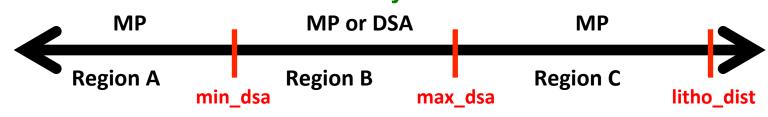
Hybrid Graph Representation

- Spacing Edge: between every pair of contacts within *litho_dist*
- 2. Grouping Edge: between every pair of neighboring contacts that can be DSA-grouped
 - *min_dsa* ≤ distance ≤ *max_dsa*
 - Collinear, on same y or x axis
 - To have 193i-manufacturable templates



Blue: Spacing Edge Red: Grouping Edge

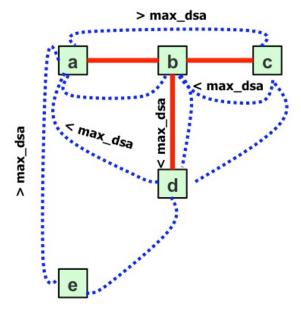
Ranges of Distance between two polygons where spacing violation can be resolved by MP or DSA



Proposed Heuristic

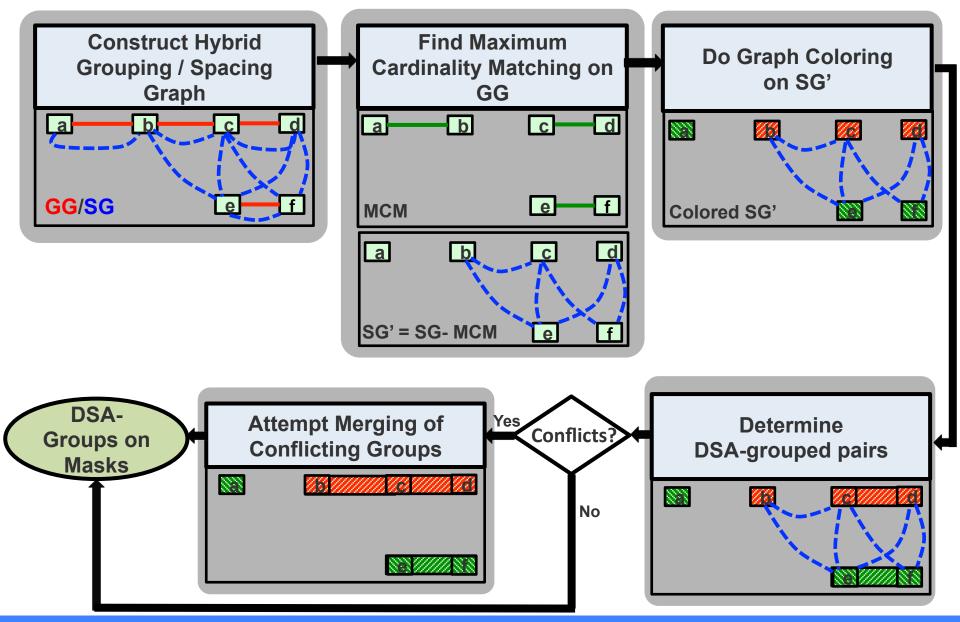
- Maximize chance of DSA grouping → maximize possibility of eliminating conflicts
- Find max number of grouping edges with no common nodes



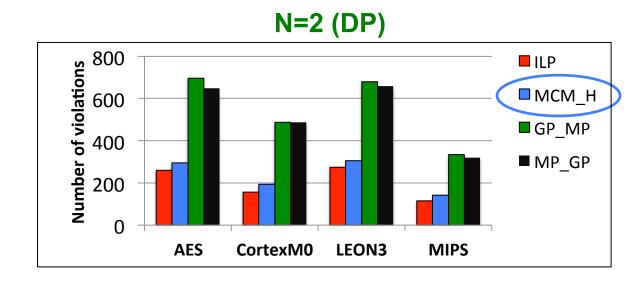


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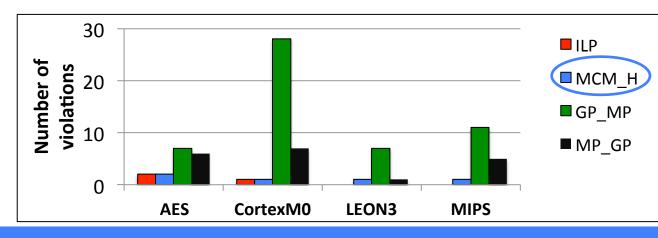
Proposed Heuristic Algorithm: MCM_H



Results



N=3 (TP)



Test case	Number of Vias
AES	48123
CortexM0	35255
LEON3	93474
MIPS	34784

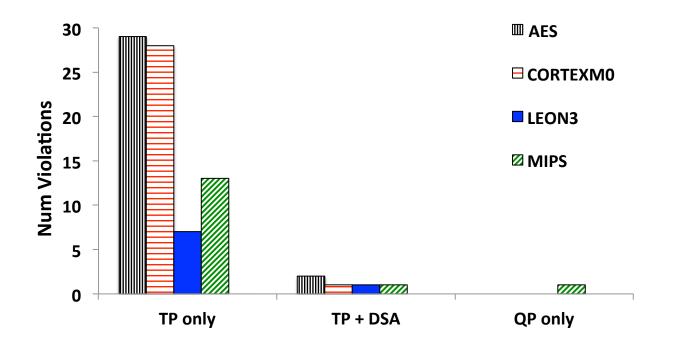
MCM_H is ~200x faster than ILP. (Max runtime on our test cases is 13s.)

MCM_H has 16.3% more violations than ILP.

MCM_H has 56% fewer violations than sequential approaches (GP_MP & MP_GP)

Can we really reduce one mask?

Number of violations with TP only, TP+DSA using MCM_H and QP only



Conclusion

- We proposed optimal ILP formulation to solve the simultaneous DSA grouping + MP decomposition problem for a hybrid DSA-MP process.
- We presented an efficient graph-based heuristic (MCM_H).
- MCM_H produces 16.3% more violations than ILP, but is ~200x faster.
- MCM_H produce 56% fewer violations than naïve sequential approaches which cascade grouping and decomposition.

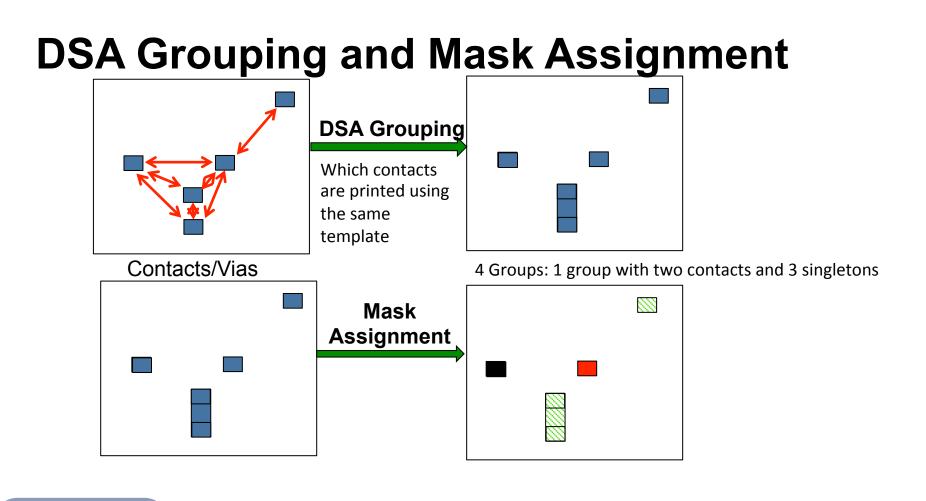
Future Work

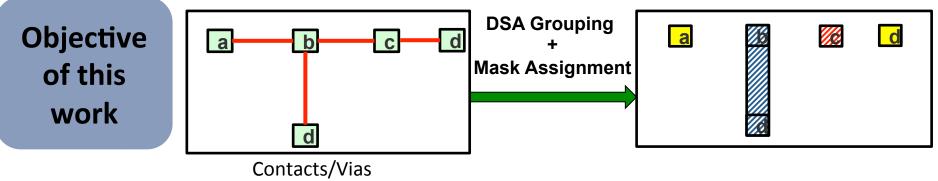
- Explore different MP+DSA integration schemes.
- Allow more flexible grouping enabled by EUV or more restricted due to Sidewall image transfer e.g. SAQP.

THANK YOU!

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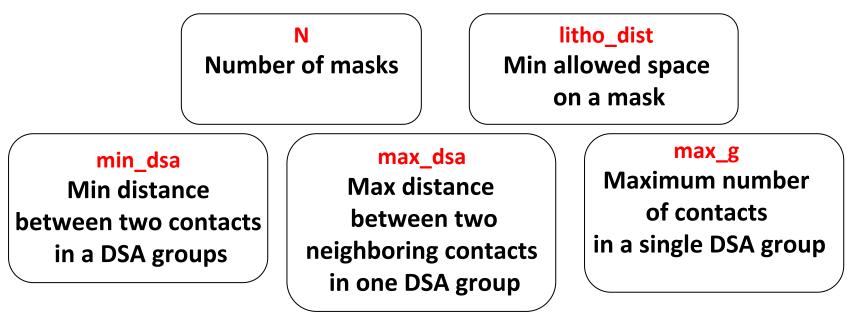
BACKUP



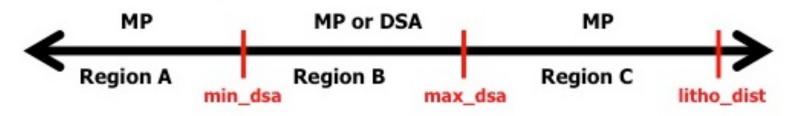


Hybrid DSA-MP Process

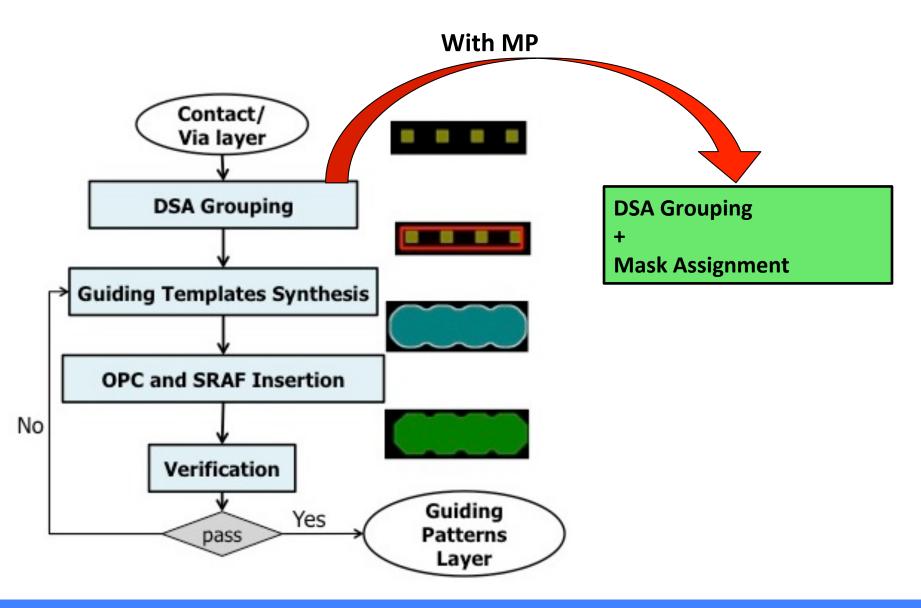
Important Parameters and Rules



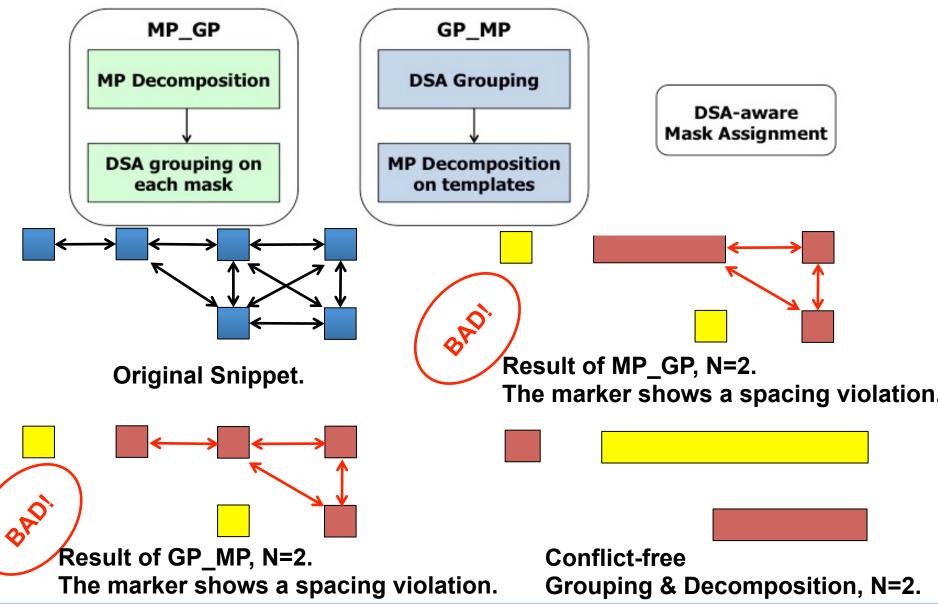
Ranges of Distance between two polygons where spacing violation can be resolved by MP or DSA



CAD flow for DSA



Alternative Flows



Experiments and Results

- Test cases have been synthesized, placed and routed using commercial 45nm SOI libraries, then scaled and sized
- Used via1 layer. After scaling: min space=21nm, via width=14nm
- Implemented in C++, using Boost library, OpenAccess
- Used Calibre Multi-patterning tool
 Number of vias in test cases
 Parameters u

Test case	Number of Vias
AES	48123
CortexM0	35255
LEON3	93474
MIPS	34784

min_dsa	20
max_dsa	42
litho_dist	66
max_g	2
contact width	14
L_0	34
N	2 (DP) and 3(TP)